



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicant** 

LIN

Application No.

10/721,288

Filed

November 26, 2003

Title

INTEGRATED CIRCUIT PACKAGING FOR

IMPROVING EFFECTIVE CHIP-BONDING AREA

**Group Art Unit** 

2824

Examiner

B. Owens

Docket No.

BHT/3183-61

## MAIL STOP AMENDMENT

Honorable Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## **AMENDMENT**

Sir:

In response to the Office Action of October 5, 2004, please amend the above-identified application as follows: